

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): R. Shane Fazzio  
Assignee: Avago Technologies, Ltd.  
Title: Microcap Wafer Bonding Apparatus  
Serial No.: 10/807,417 Filing Date: March 23, 2004  
Examiner: Monica Lewis Group Art Unit: 2822  
Docket No.: 10030899-1

San Jose, California  
March 12, 2007

Mail Stop Amendment  
Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Dear Sir:

This is a response to the December 12, 2006 Office Action, which has a statutorily shortened period for response that ends on March 12, 2007. Please amend the above-identified application as follows:

**Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 4 of this paper.